



PACKAGING

1 INTRODUCTION

Some ST62 devices can be supplied in SSOP packages, featuring high pin count capability even on small size application boards.

Pin assignment is 100% compatible with DIP or SO packages as described in the device datasheets.

2 ORDERING INFORMATION

The sales-types are similar to the DIP or SO package versions described in the device datasheet, using the "N" character to indicate the SSOP package as shown in the example below:

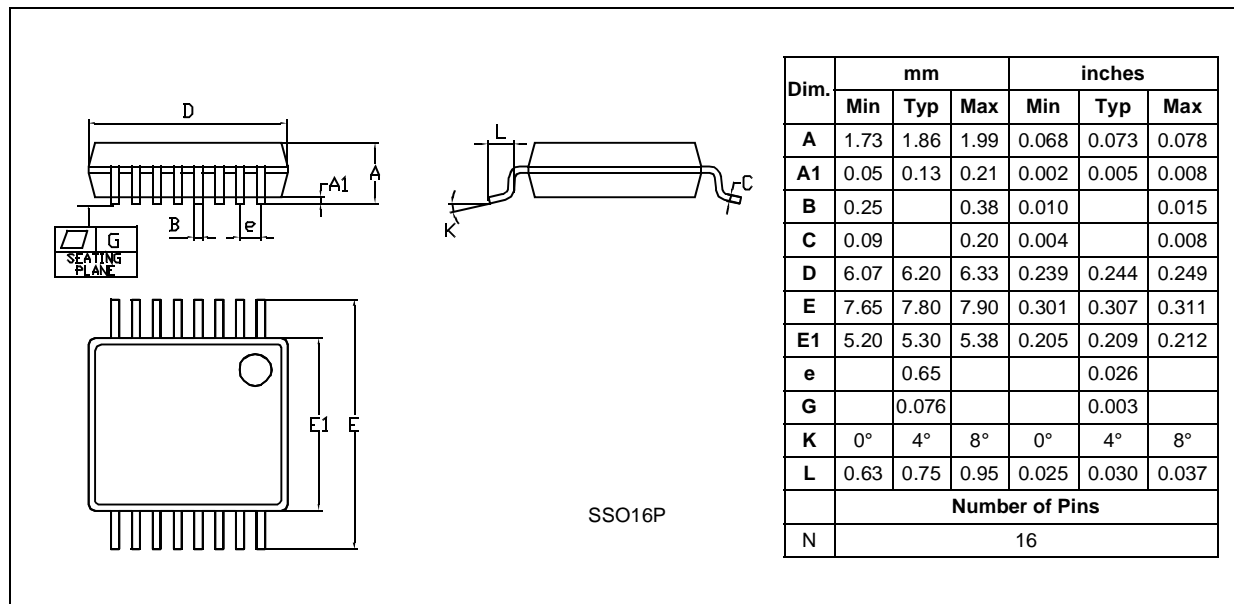
- ST62T01CB6 : PDIP16
- ST62T01CM6 : SO16
- ST62T01CN6 : SSOP16

Table 1. SSOP Package Availability

Device	OTP version	FASTROM version	Masked ROM version
ST6200C	-	SSOP16	SSOP16
ST6201C	SSOP16	SSOP16	SSOP16
ST6203C	-	SSOP16	SSOP16
ST6215C	-	SSOP28	SSOP28
ST6225C	SSOP28	SSOP28	SSOP28
ST6252C	SSOP16	SSOP16	SSOP16
ST6255C	SSOP28	SSOP28	SSOP28
ST6262C	SSOP16	SSOP16	SSOP16
ST6265C	SSOP28	SSOP28	SSOP28

3 MECHANICAL DATA

Figure 1. 16-Pin Plastic Shrink Small Outline Package, 0.209" Width



# SSOP

Figure 2. 28-Pin Plastic Shrink Small Outline Package, 0.209" Width

